



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

SEMICON Japan Meetings 2024
Thursday, December 12, 2024

Room 702, International Conference Tower 7F, Tokyo Big Sight, Tokyo, Japan
in conjunction with SEMICON Japan / OVTCCM (Hybrid)
9:00 – 12:00 JST

TC Chapter Announcements

Next TC Chapter Meeting

Friday 9:00am – 12:00pm (JST), April 18, 2025 @ Room 1, SEMI Japan office and OVTCCM

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Tsuyoshi Nagashima (Miraial), Daisuke Sado (DAIHEN), Yasuhisa Ito (Murata Machinery)

SEMI Staff: Takeaki Hirabara

<i>Company</i>	<i>First</i>	<i>Last</i>	<i>Company</i>	<i>First</i>	<i>Last</i>
Acteon NEXT LLC	Shoji	Komatsu	JEOL Ltd.	Kyoichiro	Asayama
Miraial Co., Ltd.	Tsuyoshi	Nagashima	TDK Corporation	Tsutomu	Okabe
DAIHEN Corporation	Daisuke	Sado	Intel	Stefan	Radloff
Shin-Etsu Polymer Co., Ltd.	Satoshi	Odashima	TDK Corporation	Kiyoshi	Kanashiro
Hirata Corporation	Keiji	Kanazawa	Global Net Corp.	Hiroyuki	Shida
SINFONIA TECHNOLOGY CO., LTD.	Taisuke	Matsukubo	NAURA	Clark	Cao
MURATA MACHINERY, LTD.	Yasuhisa	Ito	DAIFUKU CO., LTD.	Naoyuki	Nishizawa
<i>TOKYO SEIMITSU CO., LTD.</i>	<i>Naomune</i>	<i>Taniguchi</i>	SEMI Japan	Hirofumi	Kanno
Marubeni Plax Corporation	Luke	Igeta	SEMI Japan	Takeaki	Hirabara
Intel Corporation	Takashi	Shimizu	SEMI Japan	Keiko	Kamejinaka

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
Next Gen Assembly / Test Material Handling TF	Stefan Radloff / Intel	Shoji Komatsu / Acteon Next (New) Stefan Radloff / Intel

Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7290	Line Item Revision to SEMI E182-0424 - Specification for Panel FOUP Loadport for Panel Level Packaging	Passed as balloted

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
	SNARF	Panel Level Packaging Panel FOUP TF	Line Item Revision to SEMI E181-0424 - Specification for Panel FOUP for Panel Level Packaging
	Publication Change Request (PCR)	Panel Level Packaging Panel FOUP TF	Corrected the title of the figure - SEMI E181.3 Specification for Panel FOUP for 600 to 600 mm Panel Size and 12 Slots *As written on the part of New Business on this minutes, IP check and safety Check will be held on next meeting.
	Publication Change Request (PCR)	Panel Level Packaging Panel FOUP TF	Corrected the title of the figure - SEMI E181.4 Specification for Panel FOUP for 600 to 600 mm Panel Size and 6 Slots *As written on the part of New Business on this minutes, IP check and safety Check will be held on next meeting.

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 8 Authorized Ballots

#	When	TF	Details
	Cycle 2	Panel Level Packaging Panel FOUP TF	Line Item Revision to SEMI E181-0424 - Specification for Panel FOUP for Panel Level Packaging

Table 9 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 10 SNARF(s) Cancelled

#	TF	Title
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
20241212-1	SEMI Staff and Komatsu san	Contact the publish division to improve the check the quality of image of Standards, especially E182 (Doc # 7290)
20241212--2	SEMI Staff	Update the part “(see Regulations ¶ 16.3.1.1)” of bias on Ballot Sheet and check other points too.
20241212-3	SEMI Staff	Question about the regulations *E182: Check the regulations whether it is possible to get SNARF approval for main revision before published the standard or should be got after publication.
20241212--4	SEMI Staff	3 SNARF (1: PLP FOUP TF / 2: Next Gen TF) 2-week review -> GCS Approval

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
PIC_2024090 2-01	SEMI Staff	There is concerned that not many people will be able to attend the Global Standards Summit (GSS) all day. One idea is that if it is possible to categorize each topic, that should be coordinated with the time of the Task Force. SEMI Japan staff will suggest to the GSS Preparatory team. -> Done
PIC_2024090 2-02	SEMI Staff	Semi Japan staff will Obtain the PIP document and request for the PIP document and approval to the Publication Manager and PIC TC Co-chair. -> Done
PIC_2024090 2-03	Komatsu san	There is reported that sometimes no Roster in the TF meeting. Shoji Komatsu will notice the appropriate operations to TF leaders in the next meeting. -> Close



1 Welcome, Reminders, and Introductions

Tsuyoshi Nagashima (Miraial Co., Ltd.) called the meeting to order at 9:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1_ Required_Meeting_Element Dec 2024_JPupdated

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes
By / 2nd:	Shoji Komatsu, Acteon NEXT LLC / Daisuke Sado, DAIHEN Corporation
Discussion:	None
Vote:	12-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

Attachment: 2_Previous PIC Committee Minutes

3 Liaison Reports

3.1 PI&C North America TC Chapter

Takeaki Hirabara (SEMI Japan) reported for the TC Chapter as attached slides.

Attachment: 3_NA PIC Liaison Report Nov2024 v1

3.2 SEMI Staff Report

Takeaki Hirabara gave the SEMI Staff Report. Of notes:

- Introduction of 2024&2025 calendar of SEMICON events.
- Promotion to visit SEMICON Japan with the panel information about “SEMI IS MORE PATH”.
- Global Standards Summit 2024 - Innovating Tomorrow: Standards for Future Factories
 - Thursday, December 12 | 10:30 AM to 4:30 PM
 - Tokyo Big Sight, Conference Tower, Room 606. Everyone is invited.
 - Session Topics
 - Smart Manufacturing for Future Factories
 - Packaging Architectures & Materials
 - Environmental Sustainability
- SEMICON West 2024 will be held in Phoenix, Arizona in October. The venue of SEMICON West will alternate between Phoenix and San Francisco every October thereafter.
- SEMI Standards Friendship Party & Award Ceremony
 - Thursday, December 12: 5:00 PM – 7:00 PM
 - Room 102, Int'l Conference Tower, Tokyo Big Sight
 - All are invited.
- Information about the schedules, upcoming NA Meetings 2025 and ballots 2024 / 2025.
- Sharing about the SEMI Standards Publications and regulations & Procedure Manual updates.



- TFs have until 02/20/24 to implement use of Connect@SEMI (<https://connect.semi.org>) for TF management and document development depository. Once TFs have implemented use of Connect@SEMI, they shall use it to: maintain the TF member roster up to date, share the working drafts in PDF, and distribute the Draft Document at least one week before ballot submission to SEMI. Training materials for TF leaders and members (users) are available on the SEMI website.

Attachment: 4_ Staff Report November 2024 v4

4 Ballot Review

4.1 Document # 7290, Line Item Revision to SEMI E182-0424 - Specification for Panel FOUP Loadport for Panel Level Packaging

4.1.1 Line Item #1: Correcting an incorrect figure → Pass as balloted

4.1.2 Line Item #2: Remove KC pin height definition and optimize z160 → Pass as balloted

5 Subcommittee and Task Force Reports

5.1 Global PIC Standards Maintenance TF

No reportable matters.

5.2 Japan Electron Microscopy Workflow liaison TF

Kyoichiro Asayama reported based on the attached slides.

Attachment: 5_ EMWF TF report_20241212

5.3 Panel Level Packaging Panel FOUP TF

Shoji Komatsu reported based on the attached slides.

Attachment: 6_Panel FOUP TF report_20241212

5.4 Next Gen Assembly / Test Material Handling TF

Stefan Radloff reported based on the attached slides.

Attachment: 7_NGAT TF Dec 2024

5.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

No reportable matters.

5.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

No reportable matters.

6 Old Business

6.1 Project Period Review

None.

6.2 5 Year Review

None.



7 New Business

Voting for IP check, safety check of 2 PCRs (Corrected the title of the figure - SEMI E181.3 Specification for Panel FOUP for 600 to 600 mm Panel Size and 12 Slots / Corrected the title of the figure - SEMI E181.4 Specification for Panel FOUP for 600 to 600 mm Panel Size and 6 Slots Having) will be held on next meeting.

8 Next Meeting and Adjournment

Friday 9:00am – 12:00pm (JST), April 18, 2025 @ Room 1, SEMI Japan office and OVTCCMSee <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 12:00

Respectfully submitted by:

Takeaki Hirabara

Standards & EHS

SEMI Japan

Email: thirabara@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Miraial)	January 10, 2025
Daisuke Sado (DAIHEN)	January 8, 2025
Yasuhisa Ito (MURATA MACHINERY)	January 10, 2025

Table 14 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
1_ Required_Meeting_Element Dec 2024_JPupdated	2_Previous PIC Committee Minutes
3_ NA PIC Liaison Report Nov2024 v1	4_ Staff Report November 2024 v4
5_ EMWF TF report_20241212	6_ Panel FOUP TF report_20241212
7_ NGAT TF Dec 2024	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.